

Index

1. IPM L-series Features
2. Product Line-up
3. Term Explanation
4. Numbering System
5. Structure
6. Correct and Safety Use of Power Module
7. Reliability
 - 7-1. Introduction
 - 7-2. Basic Concepts of Semiconductor Device Reliability
 - 7-3. Mitsubishi's Quality-Assurance Program
 - 7-4. Reliability Testing
 - 7-5. Failure Analysis
 - 7-6. Derating and Reliability Projections
 - 7-7. Conclusion
8. Installation of power Module
 - 8-1. Installing Capacitor
 - 8-2. Installation Hints
 - 8-3. Thermal Impedance Considerations & Chip Layout
 - 8-4. Coating Method of Thermal Grease (Example)
9. Using IPM
 - 9-1. Applications of IPM L-series
 - 9-2. Interface of control side of IPM
 - 9-3. Control Power supply of IPM
 - 9-4. Fault Signal of IPM
 - 9-5. Other notice of using IPM
10. Power Loss and Junction Temperature
11. Average Power Loss Simplified Calculation
12. Notice for safe Designs and when Using This Specification